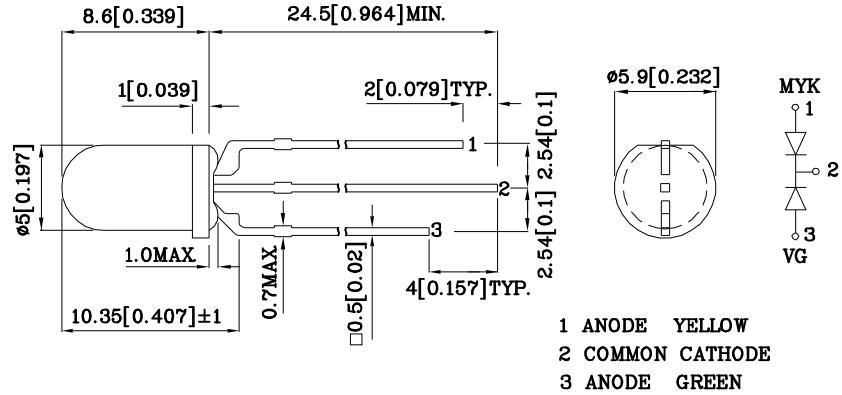


### Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant



### Package Schematics



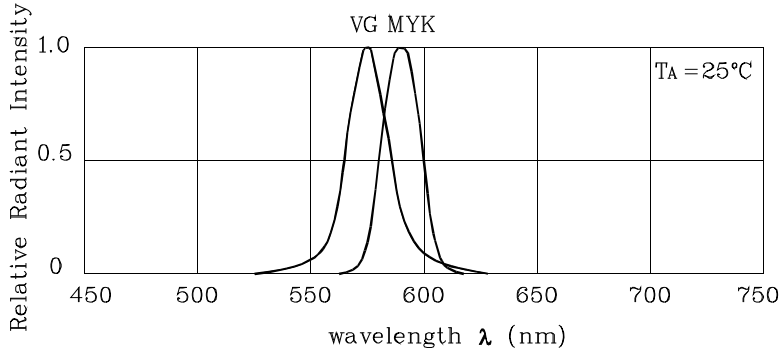
Notes:  
 1. All dimensions are in millimeters (inches).  
 2. Tolerance is ±0.25(0.01") unless otherwise noted.  
 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MYK (AlGaInP)	VG (AlGaInP)	Unit
Reverse Voltage	V <sub>R</sub>	5	5	V
Forward Current	I <sub>F</sub>	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	175	150	mA
Power Dissipation	P <sub>D</sub>	75	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85		°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

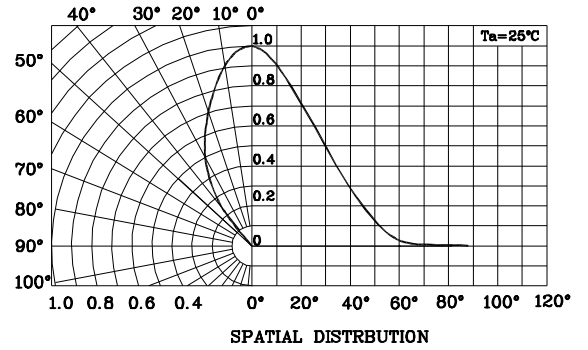
Operating Characteristics (T <sub>A</sub> =25°C)		MYK (AlGaInP)	VG (AlGaInP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2	2.1	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.5	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λ <sub>P</sub>	590*	574*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λ <sub>D</sub>	590*	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	20	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	20	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =20mA) mcd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XLMYKVG59M	Yellow	AlGaInP	White Diffused	280*	500*	590*	60°
	Green	AlGaInP		80*	180*	574*	

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

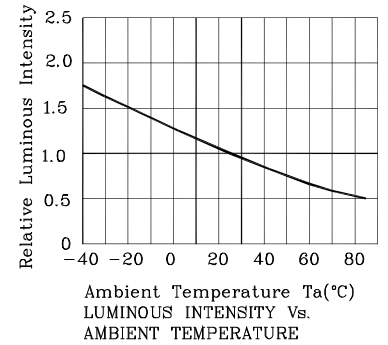
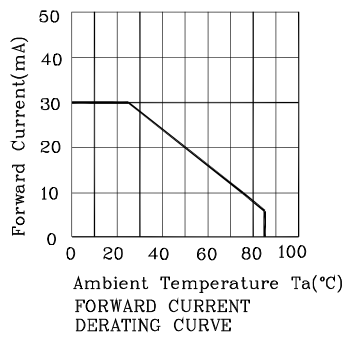
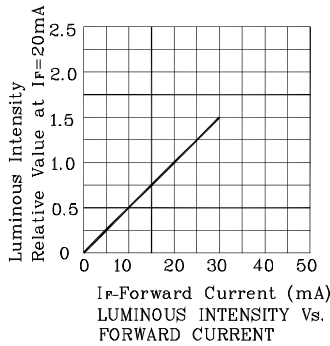
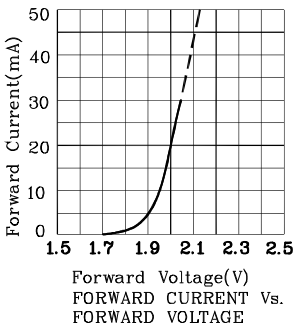


RELATIVE INTENSITY Vs. CIE WAVELENGTH

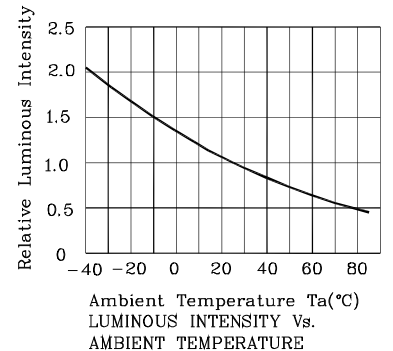
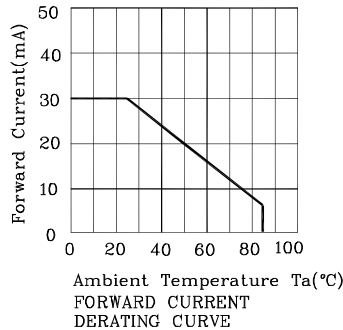
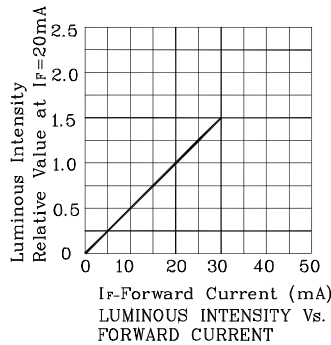
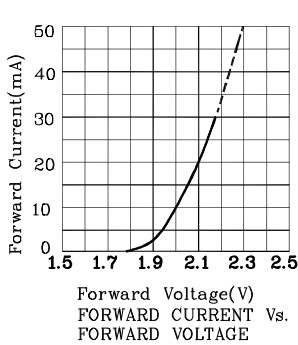


SPATIAL DISTRIBUTION

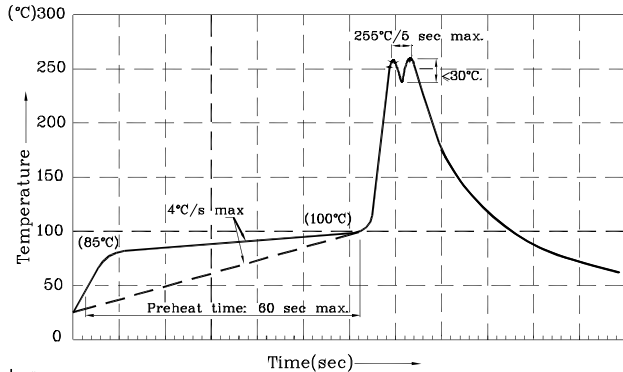
❖ MYK



❖ VG



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



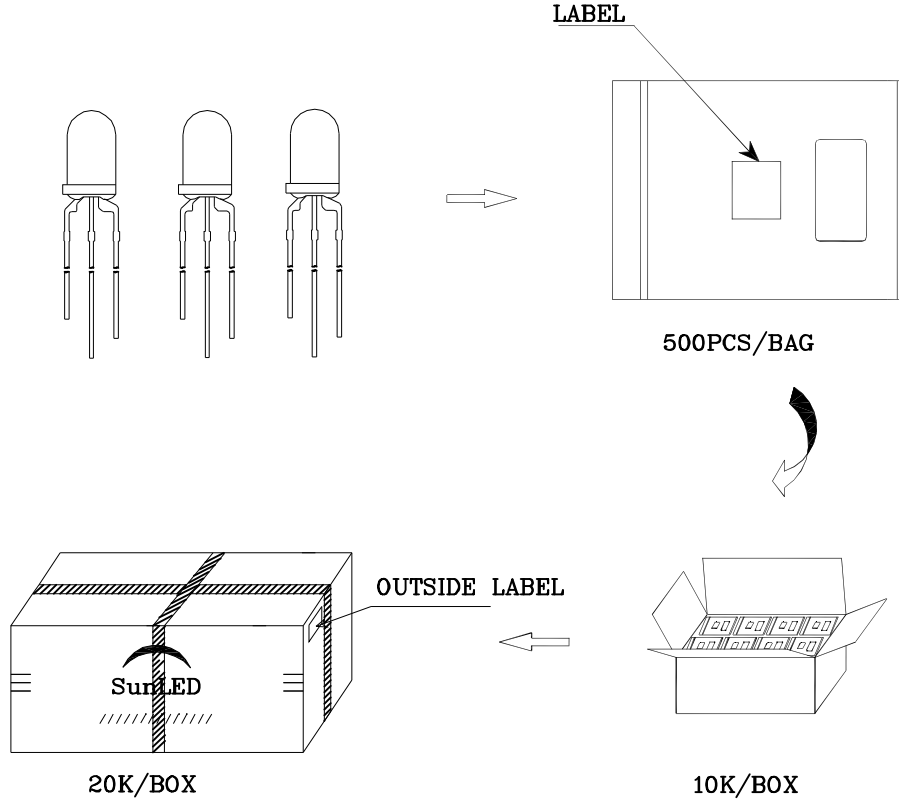

- Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
  2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
  3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
  4. Fixtures should not incur stress on the component when mounting and during soldering process.
  5. SAC 305 solder alloy is recommended.
  6. No more than one wave soldering pass.

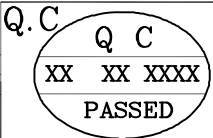

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
  2. Luminous Intensity / Luminous Flux: +/-15%
  3. Forward Voltage: +/-0.1V
- Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

	
P/NO : XLxxx59x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	